



Material Content Data Sheet



Sales Product Name				BTS50025-1TAD		Issued		1. August 2018	
MA#				MA001489916					
Package				PG-TO263-7-10		Weight*		1554.11 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	8.371	0.54	0.54	5387	5387	
leadframe	non noble metal	iron	7439-89-6	0.823	0.05		530		
	inorganic material	phosphorus	7723-14-0	0.247	0.02		159		
	non noble metal	copper	7440-50-8	822.375	52.92	52.99	529161	529850	
wire	non noble metal	aluminium	7429-90-5	9.676	0.62	0.62	6226	6226	
encapsulation	organic material	carbon black	1333-86-4	8.429	0.54		5424		
	plastics	epoxy resin	-	92.723	5.97		59663		
	inorganic material	silicondioxide	60676-86-0	460.806	29.65	36.16	296507	361594	
leadfinish	non noble metal	tin	7440-31-5	12.163	0.78	0.78	7826	7826	
plating	inorganic material	phosphorus	7723-14-0	0.007	0.00		5		
	non noble metal	nickel	7440-02-0	2.941	0.19	0.19	1892	1897	
glue	plastics	Polyimide	26023-21-2	0.198	0.01	0.01	128	128	
solder	noble metal	silver	7440-22-4	0.115	0.01		74		
	non noble metal	tin	7440-31-5	0.092	0.01		59		
	non noble metal	lead	7439-92-1	4.386	0.28	0.30	2822	2955	
heatspreader	non noble metal	iron	7439-89-6	0.131	0.01		84		
	inorganic material	phosphorus	7723-14-0	0.039	0.00		25		
	non noble metal	copper	7440-50-8	130.589	8.40	8.41	84028	84137	
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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